

SOT1432-1

plastic thin fine-pitch ball grid array package; 321 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA
Package type industry code	TFBGA321
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	17-11-2014

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	12.9	-	13	13.1	mm
E	package width	12.9	-	13	13.1	mm
A	seated height	1.05	-	1.12	1.19	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	321	-	



2. Package outline

TFBGA321: plastic thin fine-pitch ball grid array package; 321 balls SOT1432-1

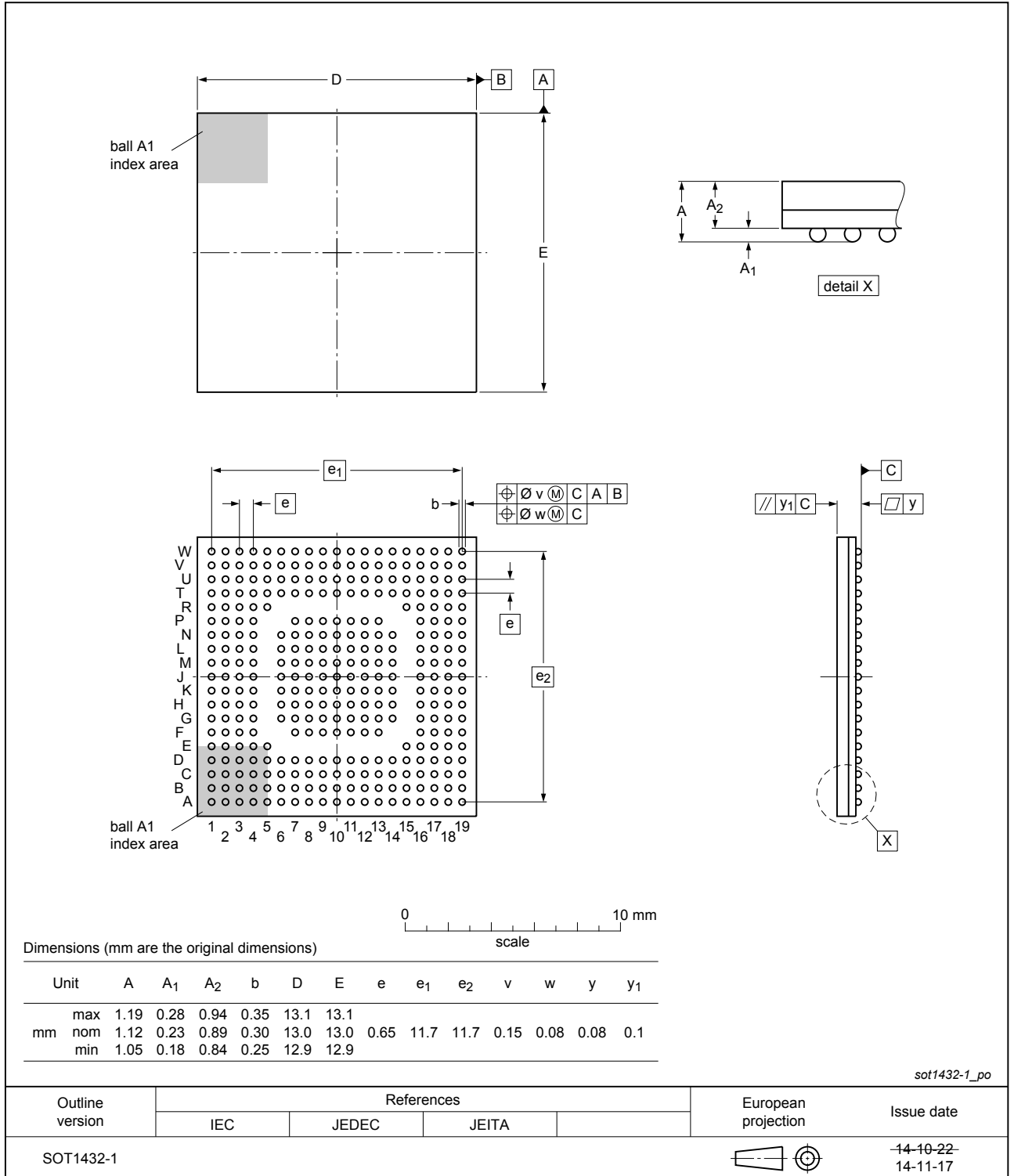


Fig. 1. Package outline TFBGA321 (SOT1432-1)

3. Legal information

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